




Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F205VGT6 STM32F205VGT6TR	931L*411XXX2	B	959	2018-03-10
	Amount	UoM	Unit type	ST ECOPACK Grade
	681.44	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Matte Tin(Sn)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	14x14x1.4	100	L Bend	
Comment	Package : 1L LQFP 100 14x14x1.4 1 0086901			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	931L*411XXX2				6000000.0	995607.0
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	13.360	mg	supplier	die	Silicon (Si)	7440-21-3		12.860	mg	962575	18872
				supplier	metallization	Aluminium (Al)	7429-90-5		0.024	mg	1796	35
				supplier	metallization	Copper (Cu)	7440-50-8		0.211	mg	15793	310
				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	75	1
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.068	mg	5090	100
				supplier	metallization	Titanium (Ti)	7440-32-6		0.003	mg	225	4
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	150	3
				supplier	Passivation	Silicon Nitride	12033-89-5		0.054	mg	4042	79
				supplier	Passivation	Silicon Oxide	7631-86-9		0.137	mg	10254	201
				supplier								
LEADFRAME	M-011 Other inorganic materials	156.345	mg	supplier	ALLOY	Copper (Cu)	7440-50-8		147.008	mg	940282	215731
				supplier	ALLOY	Iron (Fe)	7439-89-6		3.621	mg	23160	5314
				supplier	ALLOY	Iron Phosphide (Fe2P)	1310-43-6		0.045	mg	288	66
				supplier	ALLOY	Zinc (Zn)	7440-66-6		0.181	mg	1158	266
				supplier	SPOT	Silver (Ag)	7440-22-4		5.490	mg	35112	8056
DIE ATTACH	M-011 Other inorganic materials	2.904	mg	supplier	GLUE	Silver (Ag)	7440-22-4		2.483	mg	855000	3644
				supplier	GLUE	Dodecyl acrylate	2156-97-0		0.073	mg	25000	107
				supplier	GLUE	methylene diacrylate	42594-17-2		0.232	mg	80000	341
				supplier	GLUE	Diglycidylphenyl glycidyl ether	13561-08-5		0.058	mg	20000	85
				supplier	GLUE	Isobornyl Methacrylate	7534-94-3		0.029	mg	10000	43
				supplier	GLUE	dimethylbenzyl peroxide	80-43-3		0.029	mg	10000	43
BONDING WIRE	M-011 Other inorganic materials	1.534	mg	supplier	BONDING WIRE	Silver (Ag)	7440-22-4		1.480	mg	965000	2172
				supplier	BONDING WIRE	Gold (Au)	7440-57-5		0.008	mg	5000	11
				supplier	BONDING WIRE	Palladium (Pd)	7440-05-3		0.046	mg	30000	68
ENCAPSULATION	M-011 Other inorganic materials	501.840	mg	supplier	MOLDING COMPOUND	Silica, vitreous	60676-86-0		434.460	mg	865733	633168
				supplier	MOLDING COMPOUND	Epoxy Resin	Proprietary		37.158	mg	74044	54529
				supplier	MOLDING COMPOUND	Phenol Resin	Proprietary		24.772	mg	49363	36353
				supplier	MOLDING COMPOUND	3-Mercaptopropyl trimethoxysilane	4420-74-0		2.477	mg	4936	3635
				supplier	MOLDING COMPOUND	Quartz	14808-60-7		1.486	mg	2962	2181
FINISHING	M-011 Other inorganic materials	5.457	mg	supplier	MOLDING COMPOUND	Carbon black	1333-86-4		1.486	mg	2962	2181
				supplier	COATING	Tin (Sn)	7440-31-5		5.457	mg	1000000	8008